



# Product Change Notification

## 109316 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 109316 - 00  
**Change Title:** Intel(R) Server Chassis SC5400, PCN 109316-00, Product Material, Packaging change  
**Date of Publication:** April 07, 2009

## Key Characteristics of the Change:

Product Material

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Apr 19, 2009
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## Description of Change to the Customer:

Following packaging changes are being made to the Intel(R) Server Chassis SC5400.

The foam inside the carton is to be changed to a new type of foam. The new type of foam has improved quality and meets the spec of density  $\geq 35\text{kg/m}^3$  and sealing force  $\geq 50\text{kgf}$ .

The carton material is also to be changed to improve carton quality to meet the spec of compression  $\geq 700\text{kgf}$  and burst strength  $\geq 24\text{kgf/cm}^2$ . The package size is also to be changed as in below:

The inner size of the package is to be changed from 868x579x345mm to 868x579x325mm;

The outer size of the package is to be changed from 884x595x365mm to 884x595x345mm.

The changes will result in better package quality and reduce the risk of potential package damage issue.

## Customer Impact of Change and Recommended Action:

Intel recommends customer to evaluate the new package when available.

## Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change MM#	Post Change TA
SC5400BASE 877757	877757	D33731-009	877757	D33731-010
SC5400BRP 877804	877804	D33733-010	877804	D33733-011
SC5400LX 877844	877844	D33732-009	877844	D33732-010
SC5400LXI 889156	889156	D86844-005	889156	D86844-006

## Reference Documents / Attachments:

**Document:**

**Location #:**

**PCN Revision History:**

**Date of Revision:**  
April 7, 2009

**Revision Number:**  
00

**Reason:**  
Originally Published PCN